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TW 161336

### 495885 -- Patent Information

Published Serial No.	4 9 5 8 8 5											
Title	Method and apparatus for processing a microelectronic workpiece at an elevated temperature											
Patent type	B											
Date of Grant	2002/7/21											
Application Number	090102866											
Filing Date	2001/2/9											
IPC	H01L21/324											
Inventor	WEAVER, ROBERT A.(US) WILSON, GREGORY J.(US) MCHUGH, PAUL R.(US) ZILA, VLADIMIR(CA)											
Priority	<table><tr><td>Country</td><td>Application Number</td><td>Priority Date</td></tr><tr><td></td><td>US20000501002</td><td>2000/02/09</td></tr><tr><td></td><td>US20000733608</td><td>2000/12/08</td></tr></table>			Country	Application Number	Priority Date		US20000501002	2000/02/09		US20000733608	2000/12/08
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	US20000501002	2000/02/09										
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Applicant	<table><tr><td>Name</td><td>Country</td><td>Individual/Company</td></tr><tr><td>SEMITOOL, INC.</td><td>US</td><td>Company</td></tr></table>			Name	Country	Individual/Company	SEMITOOL, INC.	US	Company			
Name	Country	Individual/Company										
SEMITOOL, INC.	US	Company										
Abstract	An apparatus and method for processing a microelectronic workpiece at an elevated temperature. In one embodiment, the apparatus includes a workpiece support positioned to											

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engage and support the microelectronic workpiece during operation. The apparatus can further include a heat source having a solid engaging surface positioned to engage a surface of the microelectronic workpiece with at least one of the heat source and the workpiece support being movable relative to the other between a first position with the microelectronic workpiece contacting the engaging surface of the heat source and a second position with the microelectronic workpiece spaced apart from the engaging surface. The heat source is sized to transfer heat to the microelectronic workpiece at a rate sufficient to thermally process a selected material of the microelectronic workpiece when the microelectronic workpiece is engaged with the heat source. A heat sink can be positioned at least proximate to the heat source to cool both the heat source and the microelectronic workpiece.

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